



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-06-26
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SM6F6.0AY	AH3E*YFUV70D	A	Z6IA	2019-06-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	28	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
DSO	1.75 - 4.7-0.98	1	gull wing
Comment			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 8th March 2019			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die	607
Lead	2.69	soft solder	96036

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.69	soft solder	96036
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.69	soft solder	925009

Material Composition Declaration :						Mfr Item Name	AH3E*YFUV70D					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.336	mg	supplier	die	Silicon (Si)	7440-21-3		1.258	mg	941828	44929
				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	11230	535
				supplier	metallization	Gold (Au)	7440-57-5		0.009	mg	6738	321
				supplier	metallization	Nickel (Ni)	7440-02-0		0.017	mg	12728	607
				supplier	passivation	Silicon Oxide	7631-86-9		0.009	mg	6738	321
				supplier	polymer die coating	Durimide	Proprietary		0.028	mg	20738	989
Leadframe and Clip	M-004 Copper and its alloys	14.477	mg	Supplier	alloy	Copper (Cu)	7440-50-8		14.459	mg	998757	516393
				Supplier	alloy	Iron (Fe)	7439-89-6		0.014	mg	967	500
				Supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.004	mg	276	143
Soft solder	M-015 Other organic materials	2.907	mg	Supplier	solder	Tin (Sn)	7440-31-5		0.145	mg	49880	5179
				Supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.689	mg	925009	96036
				Supplier	solder	Silver (Ag)	7440-22-4		0.073	mg	25111	2607
Encapsulation	M-015 Other organic materials	8.968	mg	Supplier	mold compound	Silica, vitreous	60676-86-0		5.803	mg	647079	207250
				Supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		1.345	mg	149978	48036
				Supplier	mold compound	Aluminium hydroxide	21645-51-2		1.076	mg	119982	38429
				Supplier	mold compound	Phenol resin	9003-35-4		0.717	mg	79951	25607
				Supplier	mold compound	carbon black	1333-86-4		0.027	mg	3010	975
Connection coating	Solder	0.312	mg	Supplier	solder alloy	Tin (Sn)	7440-31-5		0.312	mg	1000000	11143